



# Final Call For Papers

## 2021 IEEE 14<sup>th</sup> International Conference on ASIC

Oct. 26-29, 2021, Crowne Plaza Kunming City Centre  
Kunming, China

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**2021 IEEE 14<sup>th</sup> International Conference on ASIC (ASICON 2021)** will be held in Kunming, China, during Oct.26-29, 2021. The conference is intended to provide an international forum for Integrated circuit designers, ASIC users, system integrators, IC manufacturers, process and device engineers, and CAD/CAE tool developers to present their latest progress, development and research results in their respective fields. The four-day event features keynote speeches, invited talks, regular paper presentations and tutorials, delivered by leading experts in the respective fields, on state-of-the-art Integrated circuits, design methodologies, devices, processes and manufacturing technologies. The Excellent Student Paper Award & Outstanding Young Scholar Paper Award will be announced at the conference. Additionally, an exhibition on EDA tools, foundry technologies, IC processing/testing facilities, and novel ASIC products will be held during the conference.

### **The Scope of the Conference**

Papers are solicited in, but not limited to, the following:

#### **I. Integrated Circuits and Design Techniques**

##### **[1] Analog IC**

- Amplifiers,
- Data converters (ADCs and DACs)
- Power management ICs and Energy Harvesting
- Clock generator,

##### **[2] Digital IC**

- Low power technique
- CPU, MCU, GPU, Embedded processors and DSP
- Machine learning IC
- Chaos/neural/fuzzy-logic circuits
- Programmable devices (PLD, EPLD, HDPLD, FPGA, etc)
- NOC

##### **[3] Wireless, Wireline telecommunication and Optic Communication IC**

- RF block circuits (LNA, Mixer, PA, Integrated Antenna and Switches),
- RF Transceiver (Transmitter, receiver, PLL in RF transceiver), RFID
- millimeter-wave circuits
- Seders
- THz circuits,
- Laser Driver, TIA, CDR,

##### **[4] Memory**

- DRAM & SRAM
- Flash memory
- Ferroelectric memory
- Phase change memory, RRAM, MRAM
- Novel memory

##### **[5] Sensor, Image Processing and Bio-medical IC**

- Sensor circuits
- Graph theory and computing
- Biomedical circuits and systems
- Wearable systems

#### **II. FPGA**

##### **[6] FPGA and DSP**

